Preface

Dear Distinguished Delegates and Guests,

2nd International Conference on Innovation Manufacturing and Engineering Management (IMEM2012) was held in Chongqing, China, from December 14-16, 2012, serving as a platform for expertise exchange. IMEM 2012 had drawn the attention of researchers from various disciplines: Manufacturing Technology, Mechanical Engineering, Engineering Management, etc.

Persons who attended the conference were engineers, scientists, managers of various companies and professors of the universities abroad and home. We have had record number of submission 611 this year. From which 169 papers have been accepted for presentation at the conference and will be published by TTP, in Applied Mechanics and Materials (AMM) Journal (ISSN: 1660-9336), which is online available in full text via the platform www.scientific.net. AMM should be indexed by EI according the previous TTP index results.

We express our special gratitude to all the members of the General Committee Chairs, Program Committee Chairs, Technical Program Committee and Steering Committee who worked so hard to prepare the conference and who supported the conference so professionally.

International Conference on Innovation Manufacturing and Engineering Management (IMEM2012) is organized by Chongqing Peipu Cultural Services Ltd., Zhejiang University, State University of New York-Oswego, Namseoul University, Shanghai Jiao Tong University, Hunan Institute of Engineering, Beijing University, and sponsored by National Natural Science Foundation of China (NSFC). Their kind support makes IMEM 2012 become possible. Especially, we should thank the TTP.

Finally, we would like to thanks all the authors, speakers and participants of this conference for taking part in and contributing to the International Conference on Innovation Manufacturing and Engineering Management.

We hope you have a unique, rewarding and enjoyable week at IMEM2012, Chongqing, China.

With our warmest regards,

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December 14-16, 2012
Chongqing, China

IMEM 2012

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